

FEATURES

Fast response, instantly clamping the transient over voltage.

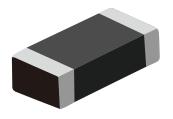
High surge current handling capability.

High energy absorption capability.

Low clamping voltages, providing better surge protection.

Low capacitance values, providing digital switching circuitryprotection.

High insulation resistance, preventing electric arcing to the adjacent devices or circuits.



APPLICATIONS

Universal Serial Bus (USB).	
Mobile communication.	
Computer/DSP product.	
Video and audio ports.	
Portable/Hand-Held Products.	
Data, Diagnostic I/O ports.	

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

ELECTRICAL SPECIFICATION

Test condition		
Varistor voltage	In = 1 mA DC	
Leakage current	Vdc = 5.5 V DC	
Maximum clamping voltage	Ic = 1 A	
Rated peak single pulse transient current	8 / 20 μs waveform, +/- each 1 time induce	
Capacitance	10/1000 μs waveform	
Insulation resistance after reflow soldering	f = 1MHz, Vrms = 0.5 V	



ELECTRICAL SPECIFICATION

Electrical specification				
Maximum allowable continuous DC voltage	5.5	V		
trigger voltage / Varistor voltage / breakdown voltage	15-25	V		
Maximum clamping voltage	45	V	Maximum	
Rated peak single pulse transient current	1	А	Maximum	
Nonlinearity coefficient	> 12			
Leakage current at continuous DC voltage	< 0.1	uA		
Response time	< 0.5	ns		
Varistor voltage temperature coefficient	< 0.05	%/°C		
Capacitance measured at 1MHz	50	pF	Typical	
Capacitance tolerance	-50 to +50	%		
Insulation resistance after reflow soldering on PCB	> 10	ΜΩ		
Operating ambient temperature	-55 to +125	°C		
Storage temperature	-55 to +125	°C		



RELIABILITY TESTING PROCEDURES

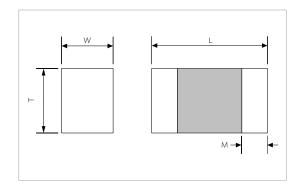
Reliability parameter		Test methods and remarks	Test requirement	
Pulse current capability	lmax 8/20 µs	IEC 1051-1, Test 4.5. 10 pulses in the same direction at 2 pulses per minute at maximum peak current	d Vn /Vn≤10% no visible damage	
Electrostatic discharge capability	ESD C=150 pF, R=330Ω	IEC 1000-4-2 Each 10 times in positive/negative direction in 10 sec at 15KV air discharge, 8KV contact discharge (Level 4)	d Vn /Vn≤10% no visible damage	
	Thermal shock	IEC 68-2-14 Condition for 1 cycle Step 1 : Min. –40 °C , 30±3 min. Step 2 : Max. +125 °C , 30±3 min. Number of cycles: 30 times	d Vn ∕Vn≤5% no visible damage	
	Low temperature	IEC 68-2-1 Place the chip at -40±5 °C for 1000±12hrs. Remove and place for 24±2hrs at room temp. condition, then measure	d Vn /Vn≤5% no visible damage	
Environmenta	High temperature	IEC 68-2-2 Place the chip at 125±5°C for 1000± 24hrs. Remove and place for 24±2hrs at room temp. condition, then measure	d Vn /Vn≤5% no visible damage	
l reliability	Heat resistance	IEC 68-2-3 Apply the rated voltage for 1000±48hrs at 85±3°C. Remove and place for 24±2hrs at room temp. condition, then measure	d Vn /Vn≤5% no visible damage	
	Humidity resistance	IEC 68-2-30 Place the chip at 40±2 °C and 90 to 95% humidity for 1000±24hrs. Remove and place for 24±2hrs at room temp. condition, then measure	d Vn ∕Vn≤5% no visible damage	
	Pressure cooker test	Place the chip at 2 atm, 120 °C, 85%RH for 60 hrs. Remove and place for 24±2hrs at room temp. condition, then measure	d Vn /Vn≤10% no visible damage	
	Operating life	Apply the rated voltage for 1000±48hrs at 125±3 °C. Remove and place for 24±2hrs at room temp. condition, then measure	d Vn /Vn≤10% no visible damage	
Mechanical Reliability	Adhesive strength	IEC 68-2-22 Applied force on SMD chip by fracture from PCB	Strength>10 N no visible damage	



MATERIAL SPECIFICATION

Body	Internal electrode	External electrode	Thickness of Ni/Sn plating layer	
ZnO based ceramics	Silver – Palladium	Silver – Nickel – Tin	Nickel $>$ 1 μ m, Tin $>$ 2 μ m	

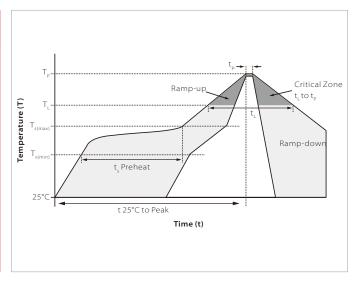
DIMENSION SPECIFICATION



Size	L(mm)	W(mm)	T(mm)	M(mm)
0402	1.0±0.10	0.5±0.10	≤ 0.6	0.20±0.10

SOLDERING RECOMMENDATIONS

	Reflow Condition	Lead-free assembly
	Temperature Max (T _{s(min)})	150°C
Pre Heat	Temperature Max (T _{s(max)})	200°C
	Time (min to max) (t_{s})	60 – 180 secs
Average ramp up rate (Liquidus Temp (T _L) to peak		3°C/second max
	$T_{s(max)}$ to T_L - Ramp-up Rate	3°C/second max
Reflow	Temperature (T _L) (Liquidus)	217°C
Reliow	Time (min to max) $(t_{\scriptscriptstyle L})$	60 – 150 seconds
Peak Temperature (T _p)		260°C
Time within 5°C of actual peak Temperature (t _n)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T,)		8 minutes max.
Do not exceed		260°C





DRDERING INF ORMATIOON

Part Number	Package&Size	QTY/Reel	Reel Size
SME0402B5.5A	0402 (1.0 x 0.5 mm)	10000PCS	7"



Headquarters

No.3387 Shendu Road Pujiang I&E Park Minhang Shanghai China 201000

Hotline

400-021-5756

Web

Https://www.semiware.com

Sales Center

Tel: 86-21-3463-7458 Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001 Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654 Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172 Ext: 8868 Email: cs03@semiware.com

By QR Code





Wehsite

Machat

To find your local partner within Semiware's global network: www.semiware.com

2022 Semiware Semiconductor Inc.

The content of this document has been carefully checked and understood. However, neither Semiware nor its subsidiaries assume any liability whatsoever for any errors or inaccuracies of this document and theconsequences thereof. Published specifications are subject to change without notice. Product suitability for any area of application must ultimately be determined by the customer. In all cases, products must never be operated outside their published specifications. Semiware does not guarantee the availability of all published products. This disclaimer shall be governed by substantive Chinese law and resulting disputes shall be settled by the courts at the place of business of Semiware. Latest publications and a complete disclaimer can be downloaded from the Semiware website. All trademarks recognized.